

# Material Composition Specification

## SOT-543 Case



Device average mass . . . . . **2.60 mg**  
 Fluctuation margin . . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	6.15%	0.16	Si	7440-21-3	6.15%	0.16	61,515
bond wire	gold or copper	1.54%	0.04	Au	7440-57-5	1.54%	0.04	15,379
				Cu	7440-50-8			
leadframe	Alloy 42	17.30%	0.45	Fe	7439-89-6	10%	0.26	99,962
				Ni	7440-02-0	7.3%	0.19	73,049
encapsulation	EMC GREEN	74.97%	1.95	silica	60676-86-0	57.67%	1.5	576,701
				epoxy resin	37382079-9	7.5%	0.195	74,971
				phenol resin	9003-35-4	7.5%	0.195	74,971
				carbon black	1333-86-4	0.19%	0.005	1,922
				metal hydroxide	1309-42-8	2.11%	0.055	21,146
plating	matte tin	0.04%	0.001	Sn	7440-31-5	0.04%	0.001	384

**Disclaimer**

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R0 (18-December 2012)